



# SQ3000S

Multi Function AOI, SPI & CMM

Optical Inspection & Metrology

[www.nordson.com/TestInspect](http://www.nordson.com/TestInspect)

**Nordson**  
*Test & Inspection*

# Nordson Test & Inspection

Founded in 1954, Nordson Corporation is a market leading industrial technology company with annual revenues of over \$2.1 billion and more than 7,500 employees worldwide.

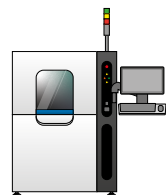
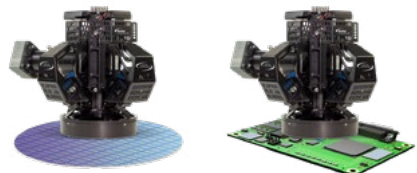
Nordson Test & Inspection offers its SMT & Semiconductor customers a robust product portfolio, including Acoustic, Optical and both Manual and Automated X-ray Inspection systems, X-ray Component Counting systems and Semiconductor measurement sensors. Nordson Test & Inspection is uniquely positioned to serve its customers with best-in-class precision technologies, passionate sales and support teams, global reach, and unmatched consultative applications expertise.

Exceptional support  
from Nordson's worldwide network

## AOI Products

### Proprietary Advanced Technology

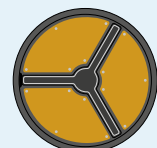
Optical Inspection  
& Metrology



## WS Products

### Improve Your Yields

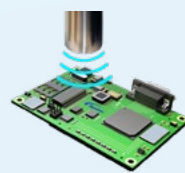
Semiconductor  
Metrology Sensors



## AMI Products

### Qualify Your Design

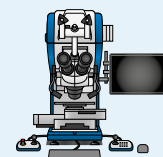
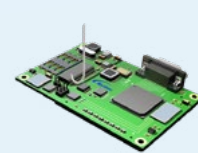
Acoustic  
Inspection



## BT Products

### Test Your Design

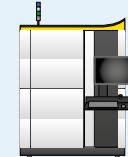
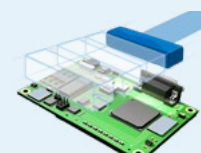
Bondtesters



## AXI Products

### High Speed High Flexibility

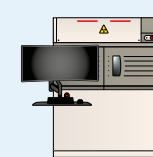
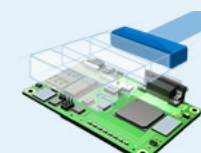
Automated  
X-ray Inspection



## MXI Products

### Making the Invisible, Visible

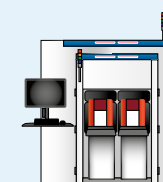
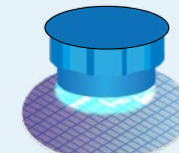
Manual  
X-ray Inspection



## AXM Products

### Measuring the Invisible

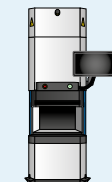
Automated  
X-ray Metrology



## CC Products

### Maximize Efficiency

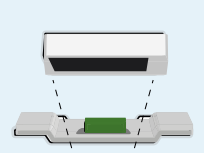
X-ray Component  
Counting



## XT Products

### High Speed High Resolution

X-ray  
Technologies





# Multi Function Advantages

The SQ3000S is an all-in-one solution that's loaded with powerful tools that cover inspection and measurement for AOI, SPI and CMM applications.

For larger boards the SQ3000S™ X offers support of large board capability of up to 710 x 610 mm board sizes.



**Shorter Inspection Times**



**Unmatched Accuracy and Resolution with MRS Technology**

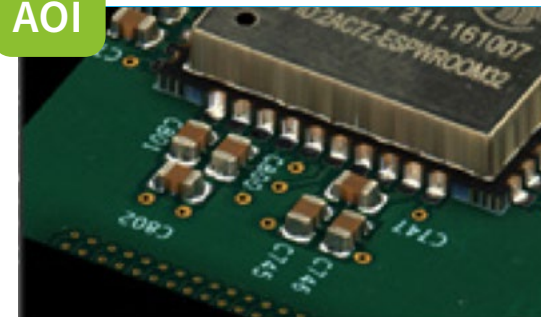


**Versatility for Applications with High Quality Requirements**

# AOI, SPI, CMM IN-LINE

The SQ3000S all-in-one is capable of performing AOI, SPI and CMM in-line.

## AOI

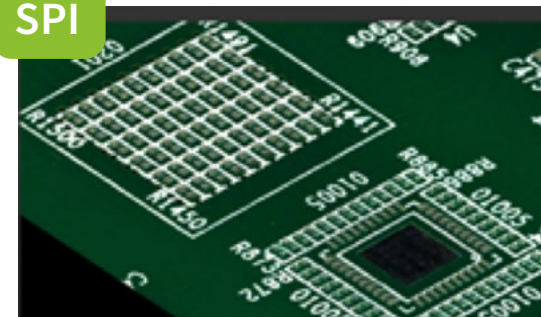


## Automated Optical Inspection (AOI)

Achieve metrology-grade accuracy at production speed enabled by MRS technology.

Attain repeatable and reproducible measurements for SMT, semiconductor, microelectronics and metrology applications.

## SPI

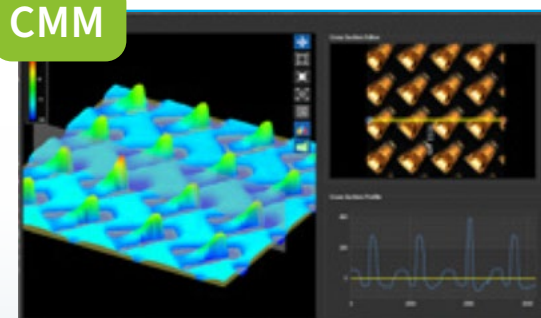


## Solder Paste Inspection (SPI)

Richer SPI Experience with Closed Loop, Feedback - Feed Forward. Optimize printing process by proactively analyzing current trend data with the standalone SPI software and Nordson Print Optimizer.

Enable smarter and faster inspection that provides reduction in rework costs, minimizes scrap and optimizes print process.

## CMM



## Coordinate Measuring Machine (CMM)

SQ3000S utilizes Nordson CMM, a comprehensive software of coordinate measurement tools which provides highly accurate, 100% metrology-grade measurement on all critical points.

A fast and easy set-up can be performed with the world's first in-line CMM system for programming complex applications.

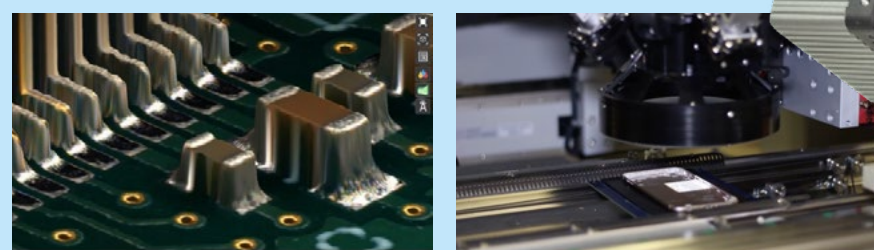


# Multi-Reflection Suppression® (MRS®) Sensor Technology

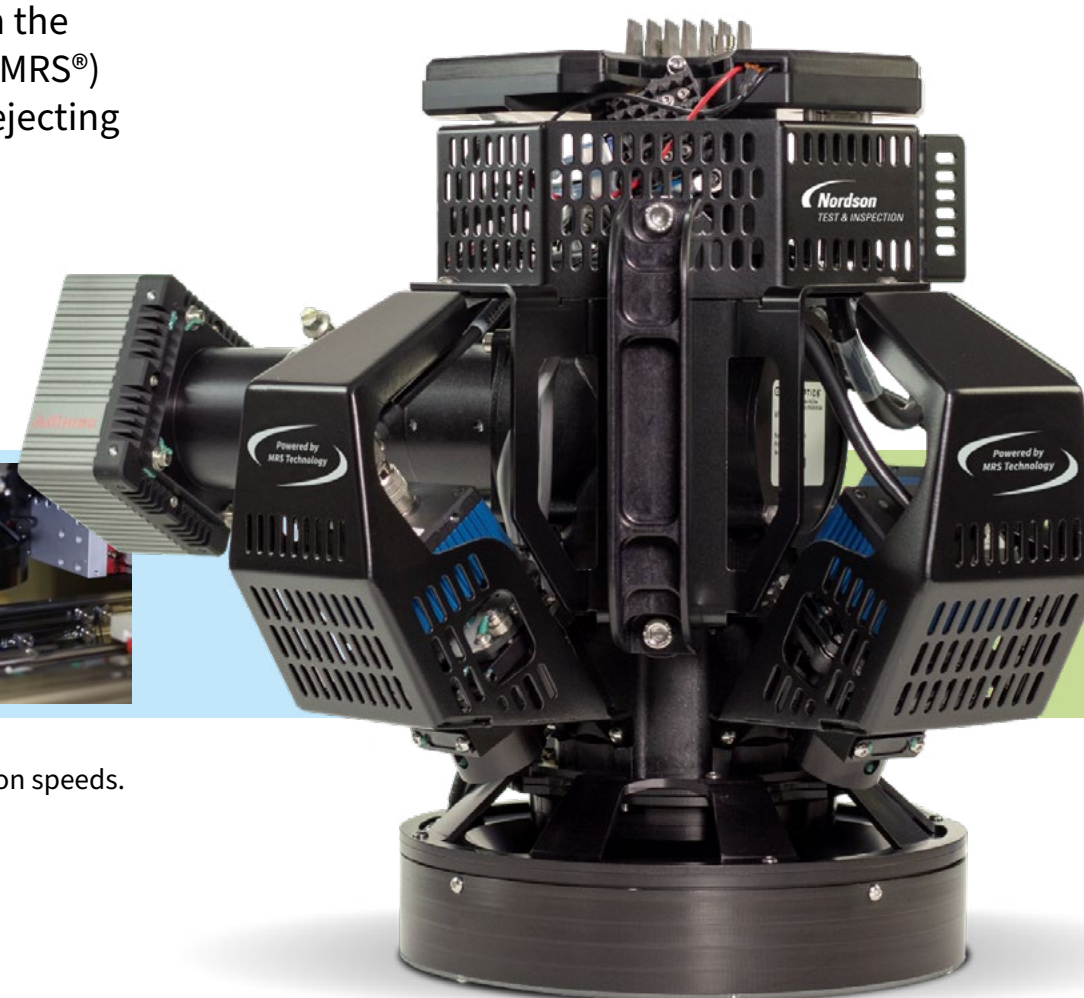
The SQ3000S offers unmatched accuracy with the revolutionary Multi-Reflection Suppression® (MRS®) technology by meticulously identifying and rejecting reflections caused by shiny components.

## Reflection based distortions

MRS is designed to Inhibit reflection-based distortions from shiny and specular surfaces.



Enabling the highest possible inspection accuracy at production speeds.



Nordson's MRS Sensor for SQ3000S 3D AOI, SPI and CMM' breakthrough 3D sensing technology comprising four multi-view 3D sensors and a parallel projector delivering metrology grade accuracy at production speed.

Nordsons' unique sensor architecture simultaneously captures and transmits multiple images in parallel while proprietary 3D fusing algorithms merge the images together. The result is ultra-high quality 3D images, accurate to sub 10 µm at production speed.

## MULTIPLE MRS SENSOR OPTIONS

Standard  
MRS Sensor

High  
Speed

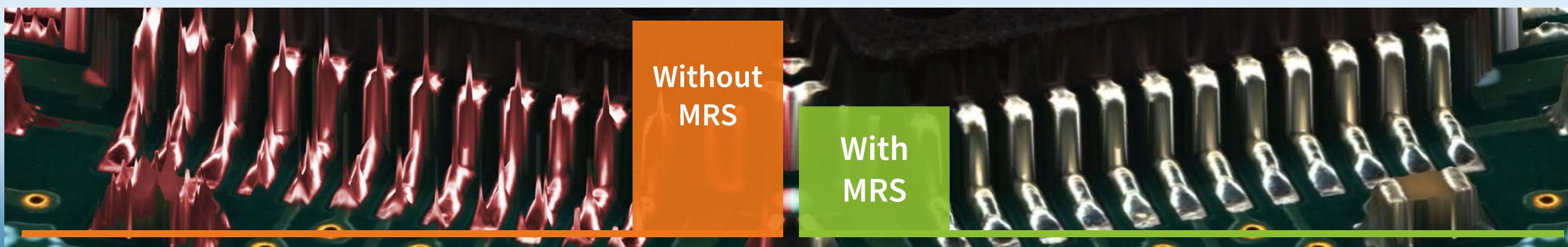
High  
Resolution

Ultra High  
Resolution

The Ultra-High Resolution MRS sensor enhances the SQ3000S platform, delivering superior inspection performance, ideally suited for the 0201 metric process and micro-electronic applications where an even greater degree of accuracy and inspection reliability is critical

Without  
MRS

With  
MRS





# Enable Smarter, Faster Inspection

The multi-award winning SQ3000S AOI software is a more powerful yet extremely simple software suite designed with an intuitive interface and multi-touch control with 3D image visualization tools.

## Ultra-fast programming capabilities

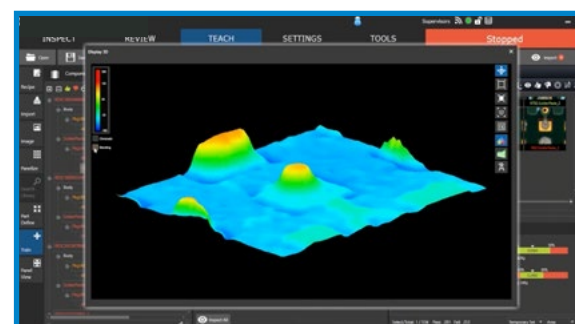
Bring the ease-of-use to a completely new level and significantly speed setup, simplify the process, reduce training efforts and minimize operator interaction – all saving time and cost.

Speed programming and performance with AI<sup>2</sup> (Autonomous Image Interpretation) technology for set-up in <13 minutes with a data-rich, pre-loaded library and automated scripts that collect and update models all on their own.

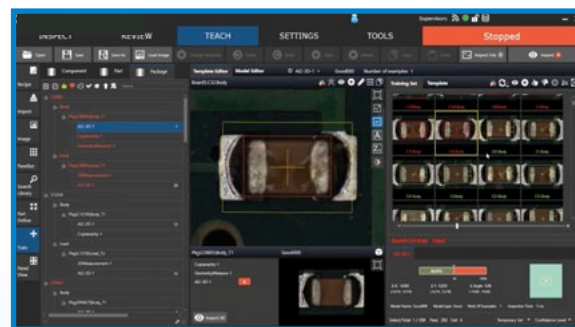
## AI<sup>2</sup> - Enable smarter, faster inspection

Inspect the most comprehensive list of features and identify the widest variety of defects. AI<sup>2</sup> offers precise discrimination with just one panel inspection making it the perfect solution for high-mix and high-volume applications.

AI<sup>2</sup> technology is all about keeping it simple - no parameters to adjust or algorithms to tune. You don't need to anticipate defects or pre-define variance either. AI<sup>2</sup> does it all for you. Powered by a data-rich, pre-loaded library and automated scripts that collect and update models all on their own.



AOI & SPI Inspection Measurement Tools - Detect even the most subtle defects, insufficient & excess solder, Solder Meniscus measurement. Additional tools include, Height, Volume, Area, XY Offset, Blob Analysis, Bridging & more.



Powerful 3D image visualisation with ultra-fast programming capabilities that brings ease-of-use to a completely new level.

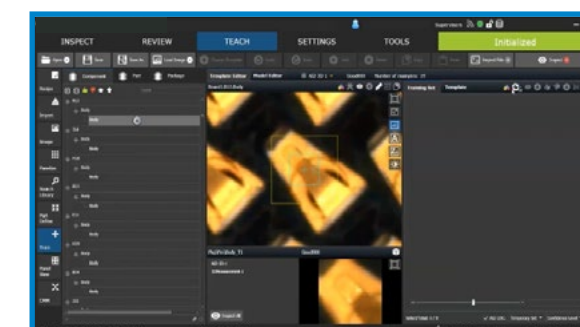
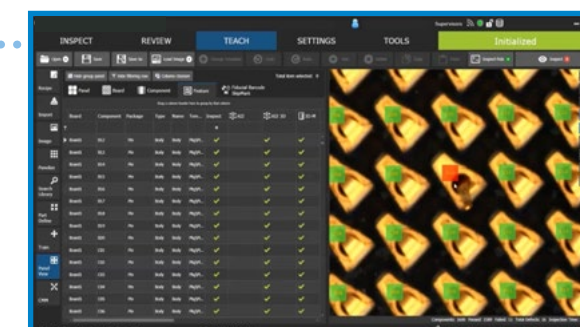
# Faster, Highly Accurate CMM Suite

Nordson Software Solutions provide our customers and partners the best added-value possible for inspection and measurement in electronics manufacturing.

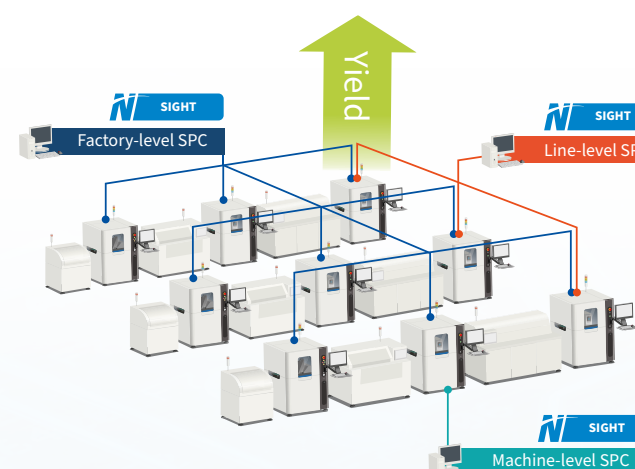


## Nordson CMM software suite

Nordson CMM's comprehensive software suite of coordinate measurement tools, provides highly accurate, 100% metrology-grade measurement on all critical points much faster than a traditional CMM, including coplanarity, distance, height and datum X, Y to name a few. A fast and easy set-up can be performed with the world's first in-line CMM system for programming complex applications as compared to slow, engineering resource-intensive set-ups that typically requires multiple adjustments with traditional coordinate measurement machines (CMMs).



Measure critical points faster than traditional measurement systems.



## Nordson Sight - Fast, scalable SPC software solution

Nordson Sight offers full-fledged machine to factory level SPC capability with powerful historical analysis and reporting tools. The software delivers complete traceability for effective process verification and yield improvement.

Nordson Sight is designed for simple set-up and intuitive use, while simultaneously delivering scalability, fast charting, and an extremely compact database size.



# High End Applications

The SQ3000S offers unmatched accuracy with the revolutionary Multi-Reflection Suppression (MRS) technology. Effective suppression of multiple reflections is critical for accurate measurement, making MRS an ideal technology solution for a wide range of applications including those with very high quality requirements.

The SQ3000S inspection and measurement capabilities include:



## Advanced Packaging

Fine pitch component • BGA solder ball • Diameter uniformity • BGA coplanarity.



## LED

Backlight • Five point & solder paste • Pad gap • Warpage coplanarity • Illumination Intensity • Adhesive squeeze out • Dye chip out.



## Advanced Socket Metrology

Pin • True position • Dispensed material • Dispensed patterns.



## Solder Paste

Tight area • Off water bridging • Jet print paste • Type 4 paste.



## Semiconductor

Highly reflective dye • Wirebond • Ribbons • Ball bond • Wirebonding • Wedgebond • Wirebond loop height • Cornerfill / Underfill.



## SMT Electronics

Microelectronics • Various electronics applications.



## Medical

Tighter tolerance • Higher demand for accuracy • Life critical • Small components, Micro electronics • Conformal coating.



## Defense

Component verification • Counterfeit part detection • High map • Point cloud output • Adhesive & epoxy.



## Aerospace

Metal module cavities • Substrate • Critical • Highly reflective material • Wire bond • Ribbon.



## Automotive

Tuning forks • Connector • True position for key features • True position for key component • High precision placement • Smaller Modules • Critical pin.



Inspection Capabilities	SQ3000S-S	SQ3000S-HS	SQ3000S-RS	SQ3000S-HR
Nordson Part Number	6283904	6283902	6283903	6283901
Inspection Speed	43 cm <sup>2</sup> /sec	52 cm <sup>2</sup> /sec	27 cm <sup>2</sup> /sec	17 cm <sup>2</sup> /sec
Minimum Component Size	0402 mm (01005 in.)		0201 mm (008004 in.)	
PCB Size	Minimum: 50 x 50 mm (2 x 2 in.); Maximum: 510 x 510 mm (20 x 20 in.)			
Component Height Clearance	Top: 50 mm (1.97 in.); Bottom: 30 mm (1.97 in.)			
Board Edge Clearance	Top: 2.5 mm (0.10 in.); Bottom: 3 mm (0.12 in.)			
PCB Thickness	0.3 to 5.0 mm ( 0.01 in. to 0.2 inc)			
Component Types Inspected	Standard SMT (chips, J-lead, gull-wing, etc.), Integrated circuits (SOIC, QFN, QFP, BGA), through-hole, odd-form, clips, connectors, header pins, LED, IPC Compliant, and more			
Component Defects	Missing, polarity, alignment, tombstone, billboard, flipped, wrong part, gross body and lead damage, and more			
Solder Joint and Other Defects	Gold finger contamination, excess solder, insufficient solder, solder volume, solder height, missing solder, bridging, through-hole pins & more			
3D Measurement Inspection	Lifted Lead, package coplanarity, polarity dimple and chamfer identification, engraving depth, gap uniformity, and more			
Measurement Gage R&R	<10% @ ±3σ (±80 μm process tolerance)			
Z Height Accuracy	1 μm on certification target			
Z Measurement Range	6 mm at spec, 24 mm capability		3 mm at spec, 8 mm capability	

CMM Capabilities	
Coordinate Measurement Capability	Line / Distance / X,Y / Mid Line, Inter Point / Regression Shifted, Datum X,Y / LSF X,Y Offset, X,Y Offset / Value / Location / List of X,Y Values, Height / Local Height / Regression / Radius, Coplanarity/ Distance to plane / 2nd Order fitting, Difference / Absolute / 2sqrt / VC, Max / Min / Ave / Sigma / Plus / Minus / Multiple
Advantage	Faster speed compared to a typical CMM machine. Single setup for inspection and CMM result
Accuracy XY / Z	6 $\mu\text{m}$ / 2 $\mu\text{m}$
Resolution XY / Z	10 $\mu\text{m}$ / 0.5 $\mu\text{m}$
Maximum Weight	3 kg / 5 kg (Option)
Min./ Max. Feature Height	Min. 50 $\mu\text{m}$ ; Max. 24mm

Vision System & AI Capabilities	
Imagers	Multi-3D sensors
Resolution	Sub 10 $\mu\text{m}$
Field of View (FOV)	36 x 30 mm      36 x 36 mm      26 x 26 mm      21 x 21 mm
Maximum Inspection Area	508 x 503 mm (20 x 19.8 in.)
Image Processing	Autonomous Image Interpretation (AI <sup>2</sup> ) Technology, Coplanarity and Lead Measurement
Nordson Intelligence	Network Based Algorithm Models, Automatic PCB Segmentation, Auto Programming, Anomaly Detection, Auto Defect Classification & more
CAD Import	Any column-separated text file (.txt) or comma-separated value file (.csv) with ref designator, XY, Angle, Part no info; Valor process preparation

System Specifications	
Machine Interface	SMEMA, RS232 and Ethernet
Power Requirements	100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps
Compressed Air Requirements	5.6 Kg/cm <sup>2</sup> to 7.0 Kg/cm <sup>2</sup> (80 to 100 psi @ 4 cfm)
System Dimensions	110 x 129 x 139 cm (W x D x H)
Weight	900 kg (2127 lbs.)

Options	
	Barcode Reader, Offline Rework Station, SPC Software, Alignment Target, Programming Software: ePM-SPI/AOI

**For more information, speak with your Nordson representative or contact your Nordson regional office**

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